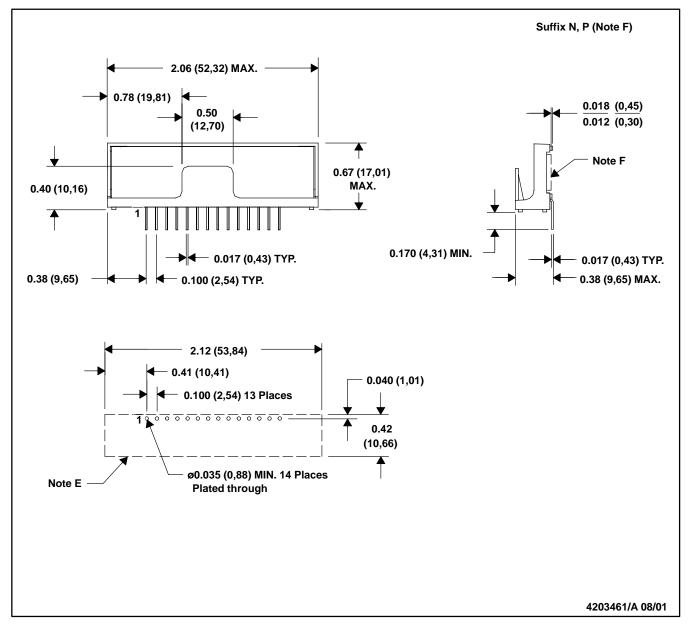
1

EDD (R-PSIP-T14)

PLASTIC SINGLE-IN-LINE MODULE



- NOTES: A. All linear dimensions are in inches (mm).
 - B. This drawing is subject to change without notice.
 - C. 2 place decimals are ± 0.030 (± 0.76 mm).
 - D. 3 place decimals are ± 0.010 ($\pm 0,25$ mm).
 - E. Recommended mechanical keep out area.
 - F. P-suffix parts include a metal heat spreader.

 The heat spreader is isolated but electrically conductive.

The near spreader is isolated but electrically conductive.

It can be grounded.

N-suffix do not include a metal heat spreader.



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